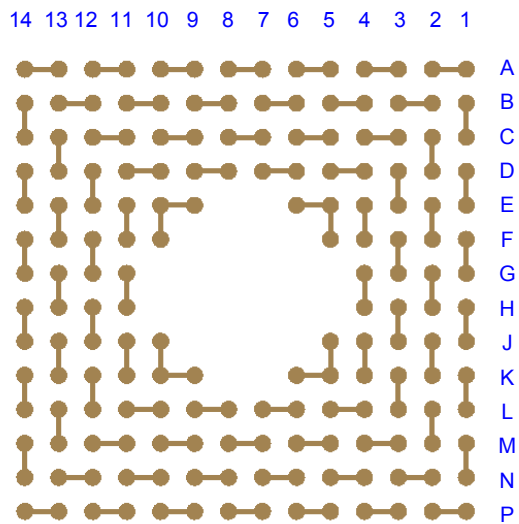


- Notes: (Unless Otherwise Specified).
- 1) ALL DIMENSIONS ARE IN MM.
 - 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
 - 3) BALL DIAMETER (BEFORE REFLOW): 0.508mm [20 MIL].
 - 4) SOLDER MASK DEFINED PAD OPENING: 0.41mm [16 MIL].
 - 5) PAD Cu DIAMETER: 0.508mm [20 MIL].
 - 6) SUBSTRATE MATERIAL: BT RESIN (2-L OR 4-LAYER).
 - 7) DUMMY DIE OPTIONAL: SINGLE OR 3X STACK (SEE PAGE 3).
 - 8) DAISY CHAIN PATTERN (SEE PAGE 2).
 - 9) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

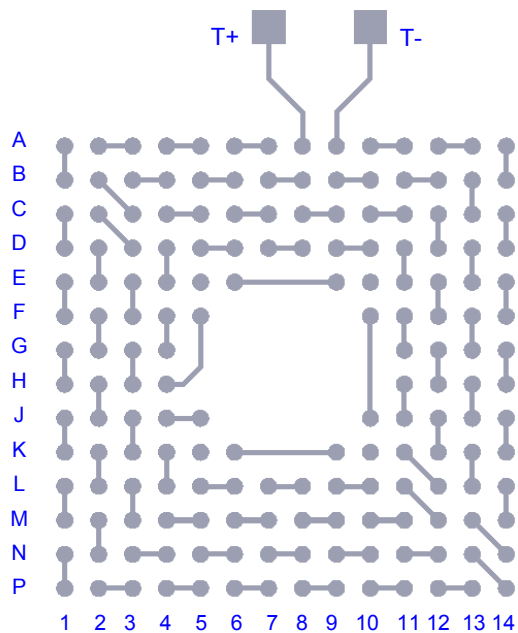
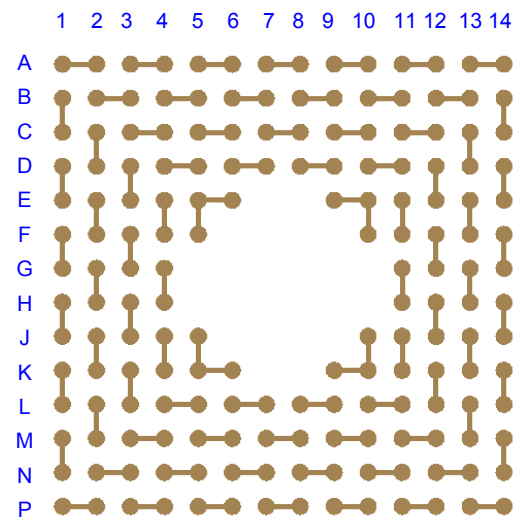
PART NUMBER TABLE					
PART NUMBER	BALL ALLOY	BALL CODE	RoHS	Si DIE	LAYERS
BGA172T1.0C-DC143D	Sn96.5/Ag3.0/Cu0.5	SAC305	YES	SINGLE	2-L
BGA172T1.0-DC143D	Sn63/Pb37	Sn63	NO	SINGLE	2-L
BGA172T1.0-DC143D3	Sn63/Pb37	Sn63	NO	3X STACK	4-L

APPROVALS		DATE				
DRAWN	T. Au	10/31/12	TITLE BGA172T1.0-DC143D DAISY CHAIN DUMMY			
ENG	M. Hart	10/31/12				
MFG						
QA			SCALE	SIZE	DRAWING NO.	REV
CUST			5.5:1	A	511430	A
REVISED			DO NOT SCALE DRAWING			SHEET 1 OF 3

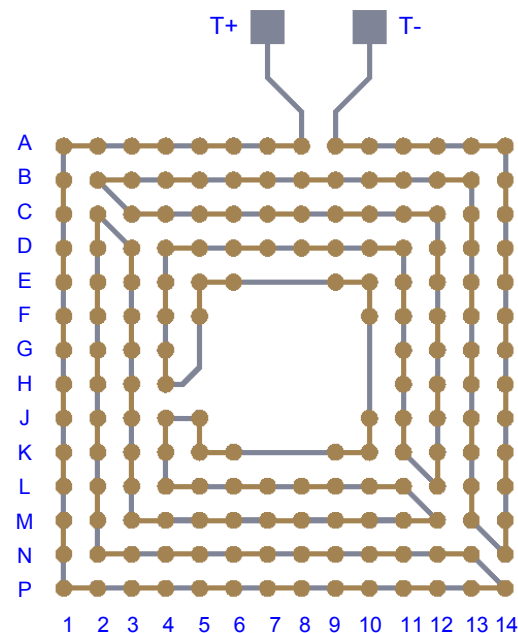
BALL VIEW



BOTTOM SIDE (TOP X-RAY VIEW)



TEST VEHICLE BOARD



AFTER MOUNTING

Notes:

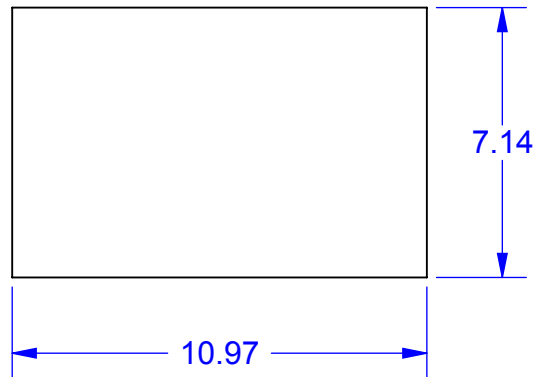
- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE. DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.508mm [20 MIL].
- 3) PCB DAISY CHAIN TRACING LINE WIDTH 0.152mm [6 MIL].
- 4) SMD (SOLDER MASK DEFINED) PAD OPENING 0.41mm [16 MIL].

TopLine [®]			
TITLE		BGA172T1.0-DC143D DAISY CHAIN DUMMY	
SCALE	SIZE	DRAWING NO.	REV
4.5:1	A	511430	A
DO NOT SCALE DRAWING			SHEET 2 OF 3

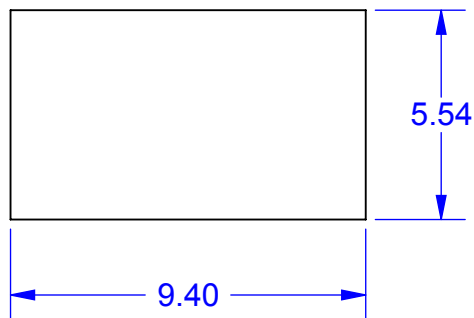
DETAIL "B"
DUMMY DIE

3X STACK DIE
PART SUFFIX - D3
TOP VIEW

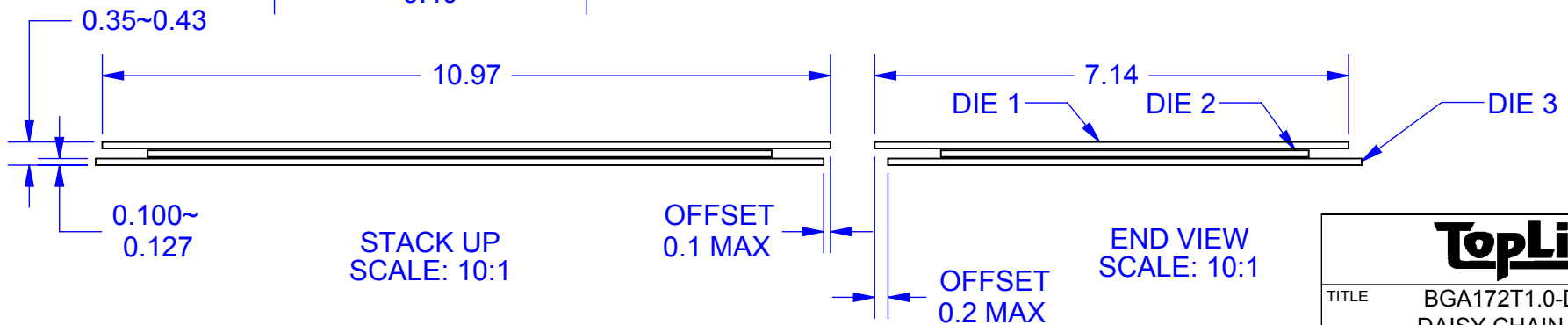
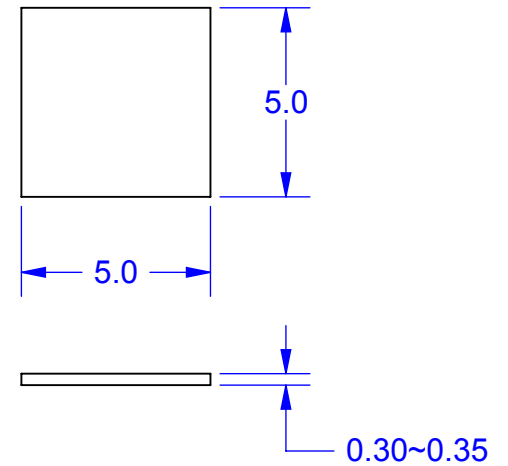
DIE 1 & 3



DIE 2



SINGLE DIE
PART SUFFIX - D



Notes:
1) SPACING BETWEEN DIE IS 25.4 μ m (1.0 MIL) X2 PLACES.

TopLine [®]			
TITLE BGA172T1.0-DC143D DAISY CHAIN DUMMY			
SCALE 5:1	SIZE A	DRAWING NO. 511430	REV A
DO NOT SCALE DRAWING			SHEET 3 OF 3